

Amendment to the Specification

Please replace paragraph [0028] with the paragraph below:

[0028] Jetting of conformal coating material onto a substrate has several advantages over existing conformal coating methods. One advantage, for example, is that jetting provides a small wetted area through the precise control of the volume of ejected droplets, which for example may be a maximum of five nanoliters. The small wetted area of conformal coating dots allows for precise coating of small areas, for example, areas of about 200 micrometers, thus enhancing the selectivity of conformal coating systems. By precisely and selectively placing the conformal coating on a substrate without overspray, edge definition between coated and uncoated areas is enhanced. Further, by eliminating overspray, only the desired areas of the substrate are coated; and undesirable machine contamination is substantially reduced. Therefore, the need for masking is essentially eliminated, thereby reducing production and maintenance costs. Further, jetting the conformal coating material permits only the reverse of the solder mask, that is, the solder joints to be coated. The net result is a substantial savings in the conformal coating material used and thus, providing additional cost savings.